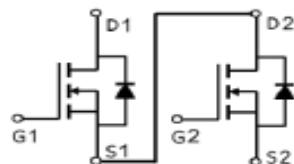
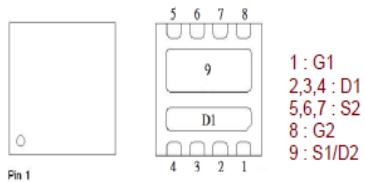


# PE642DT

## Dual N-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

	$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
Q2	30V	9mΩ @ $V_{GS} = 10V$	34A
Q1	30V	10.5mΩ @ $V_{GS} = 10V$	31A



PDFN 3X3S

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	Q2	Q1	UNITS
Drain-Source Voltage	$V_{DS}$	30	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	
Continuous Drain Current <sup>3</sup>	$I_D$	34	31	
		22	20	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	48	46	A
Continuous Drain Current <sup>3</sup>	$I_D$	11	9.7	
		8.8	7.7	
Avalanche Current	$I_{AS}$	21	18.3	
Avalanche Energy	$E_{AS}$	22	16.7	
Power Dissipation	$P_D$	20	19	W
		8	7.6	
Power Dissipation	$P_D$	2	1.7	
		1.2	1.1	
Operating Junction & Storage Temperature Range	$T_J, T_{stg}$	-55 to 150		°C

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$R_{\theta JA}$	Q2	62	°C / W
	$R_{\theta JA}$	Q1	70	
Junction-to-case	$R_{\theta JC}$	Q2	6.2	
	$R_{\theta JC}$	Q1	6.5	

<sup>1</sup>Pulse width limited by maximum junction temperature  $T_{J(MAX)}=150^\circ C$ .

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ C$ . The value in any given application depends on the user's specific board design.

<sup>3</sup>Package limitation current is Q2=14A , Q1=9.5A.

# PE642DT

## Dual N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS	
			MIN	TYP	MAX		
<b>STATIC</b>							
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	Q2	30		V	
			Q1	30			
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	Q2	1.3	1.75	2.3	
			Q1	1.3	1.75	2.3	
Gate-Body Leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	Q2		$\pm 100$	nA	
			Q1		$\pm 100$		
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 24\text{V}, V_{\text{GS}} = 0\text{V}$	Q2		1	$\mu\text{A}$	
			Q1		1		
		$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 55^\circ\text{C}$	Q2		10		
			Q1		10		
Drain-Source On-State Resistance <sup>1</sup>	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$	Q2		8	12	
		$V_{\text{GS}} = 4.5\text{V}, I_D = 9\text{A}$	Q1		13	15.5	
		$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	Q2		6.3	9	
		$V_{\text{GS}} = 10\text{V}, I_D = 9.5\text{A}$	Q1		8.6	10.5	
Forward Transconductance <sup>1</sup>	$g_{\text{fs}}$	$V_{\text{DS}} = 5\text{V}, I_D = 10\text{A}$	Q2		43	S	
		$V_{\text{DS}} = 5\text{V}, I_D = 9.5\text{A}$	Q1		45		
<b>DYNAMIC</b>							
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1\text{MHz}$	Q2		782	pF	
Output Capacitance	$C_{\text{oss}}$		Q1		616		
Reverse Transfer Capacitance	$C_{\text{rss}}$		Q2		139		
Gate Resistance	$R_g$		Q1		120		
Total Gate Charge <sup>2</sup>	$Q_g$		Q2		76		
			Q1		83		
	$V_{\text{GS}} = 10\text{V}$ $V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$ $V_{\text{GS}} = 4.5\text{V}$ $V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 9.5\text{A}$	Q2		2.3	3.5		
		Q1		2.7	4		
Gate-Source Charge <sup>2</sup>		$Q_{\text{gs}}$		Q2		18	nC
				Q1		14	
				Q2		9.6	
				Q1		7.6	
Gate-Drain Charge <sup>2</sup>		$Q_{\text{gd}}$		Q2		2.2	
				Q1		2.1	
				Q2		5.2	
				Q1		4	

## PE642DT Dual N-Channel Enhancement Mode MOSFET

Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	Q2 $V_{DS} = 15V$ , $I_D \geq 10A$ , $V_{GS} = 10V$ , $R_{GEN} = 6\Omega$ Q1 $V_{DS} = 15V$ , $I_D \geq 9.5A$ , $V_{GS} = 10V$ , $R_{GEN} = 6\Omega$	Q2		27		nS
Rise Time <sup>2</sup>	$t_r$		Q1		18		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$		Q2		24		
Fall Time <sup>2</sup>	$t_f$		Q1		24		
			Q2		47		
			Q1		44		
			Q2		25		
			Q1		23		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ C</math>)</b>							
Continuous Current <sup>3</sup>	$I_S$	$I_F = 10A$ , $V_{GS} = 0V$ $I_F = 9.5A$ , $V_{GS} = 0V$	Q2			16	A
Forward Voltage <sup>1</sup>	$V_{SD}$		Q1			17	
Reverse Recovery Time	$t_{rr}$	Q2 $I_F = 10A$ , $dI_F/dt = 100A/\mu S$ Q1 $I_F = 9.5A$ , $dI_F/dt = 100A/\mu S$	Q2			1.2	V
Reverse Recovery Charge	$Q_{rr}$		Q1			1.1	
			Q2		10.5		nS
			Q1		9.3		
			Q2		2.8		nC
			Q1		2.2		

<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu sec$ , Duty Cycle  $\leq 2\%$ .

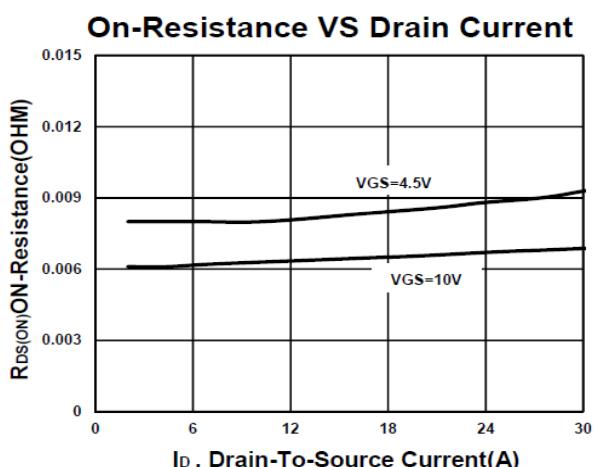
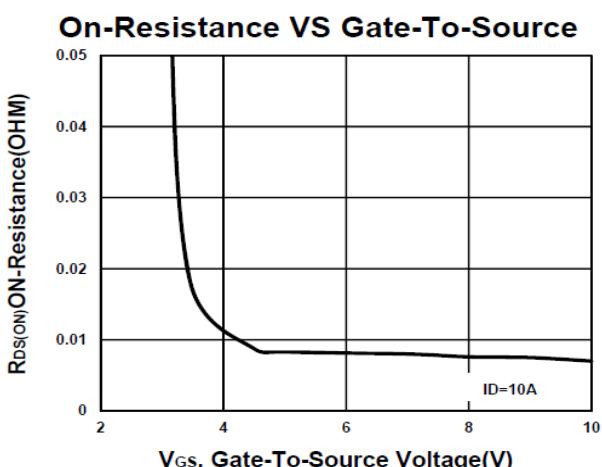
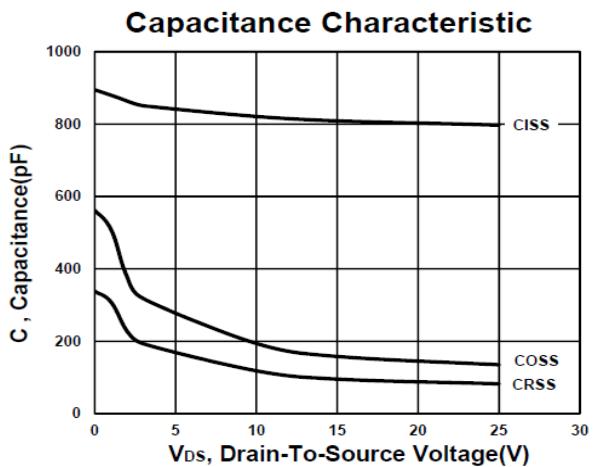
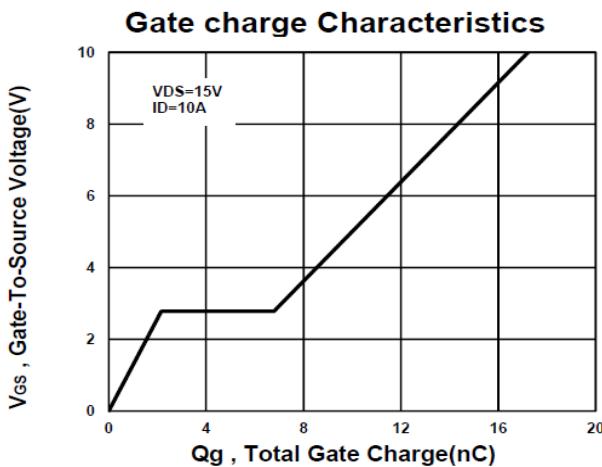
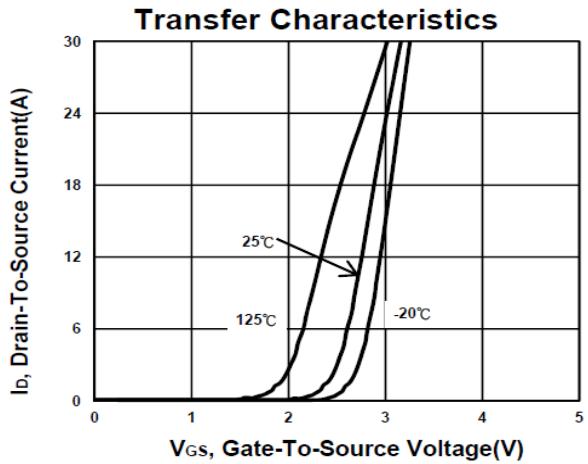
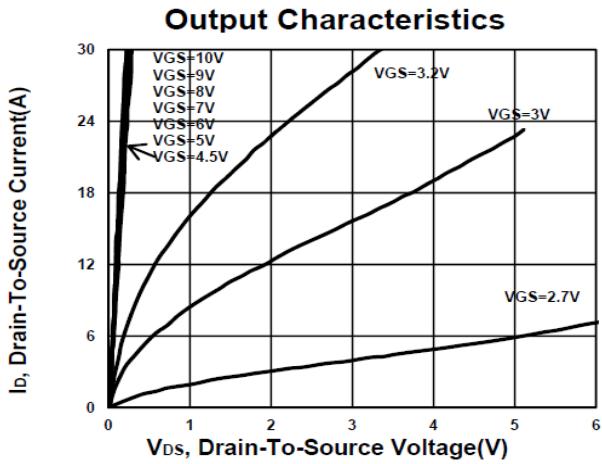
<sup>2</sup>Independent of operating temperature.

<sup>3</sup>Package limitation current is Q2=14A , Q1=9.5A.

# PE642DT

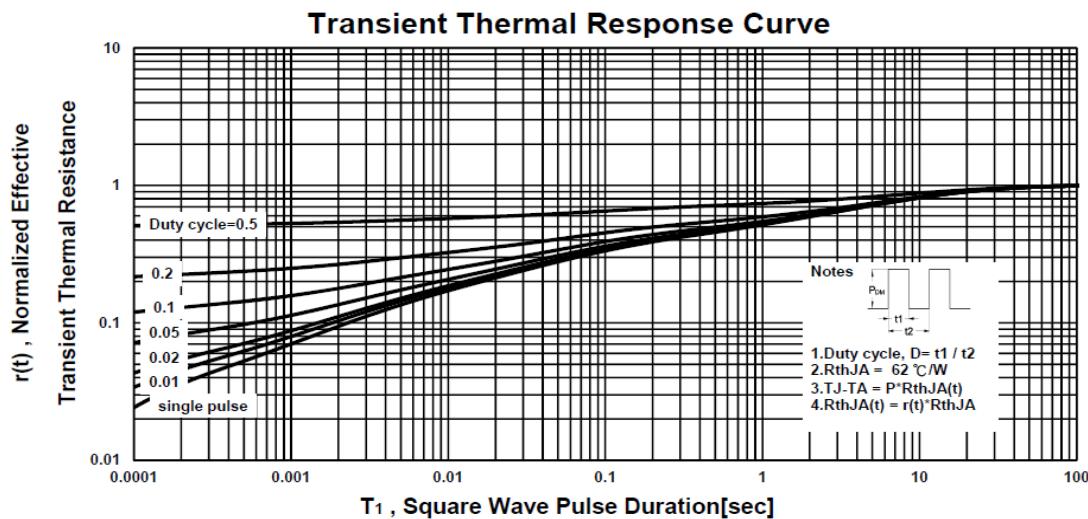
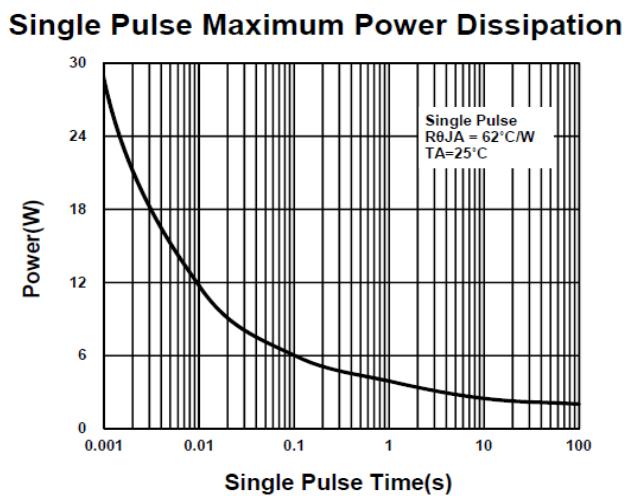
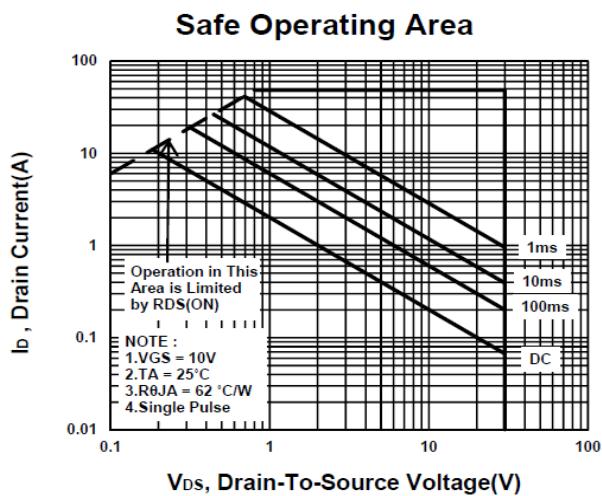
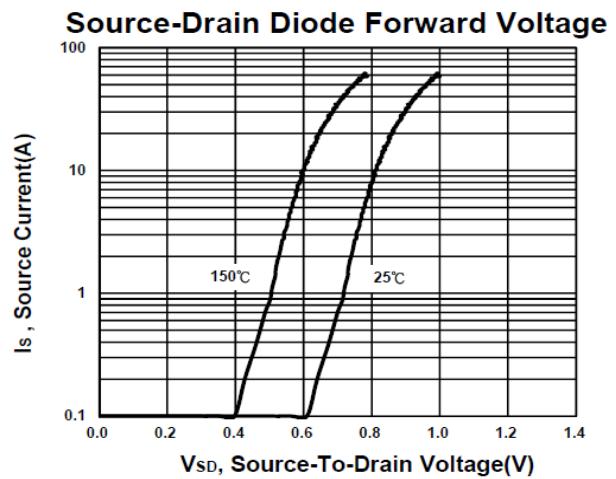
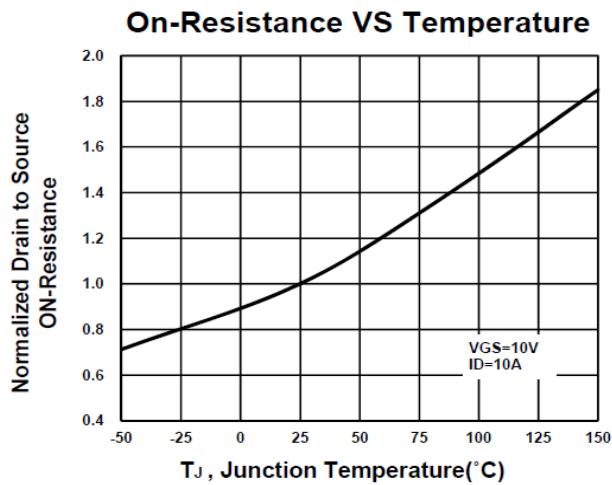
## Dual N-Channel Enhancement Mode MOSFET

### TYPICAL PERFORMANCE CHARACTERISTICS Q2



# PE642DT

## Dual N-Channel Enhancement Mode MOSFET

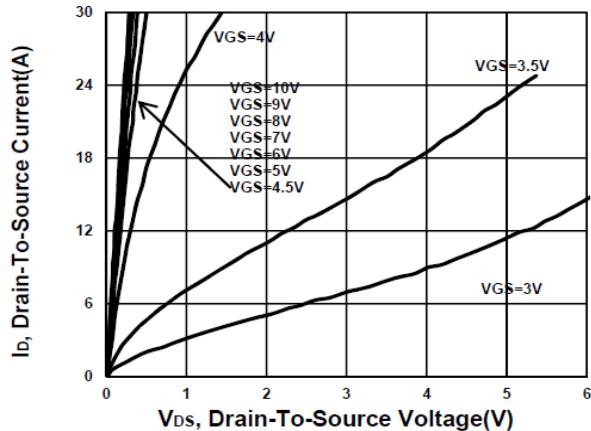


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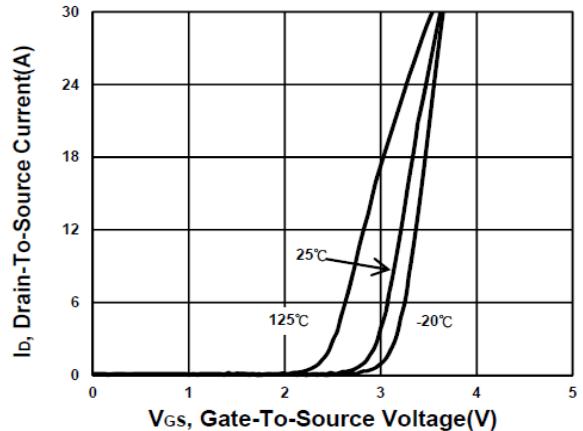
## Dual N-Channel Enhancement Mode MOSFET

**Q1**

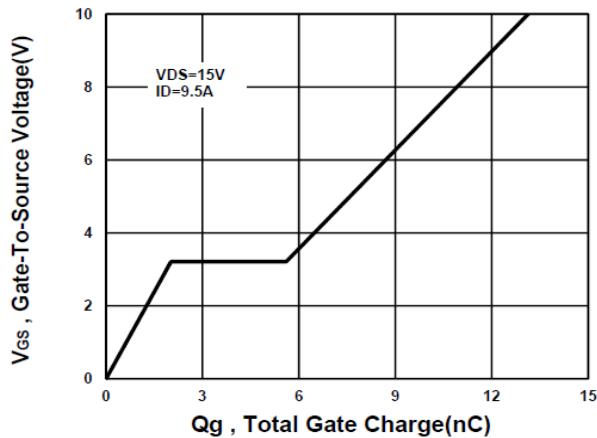
**Output Characteristics**



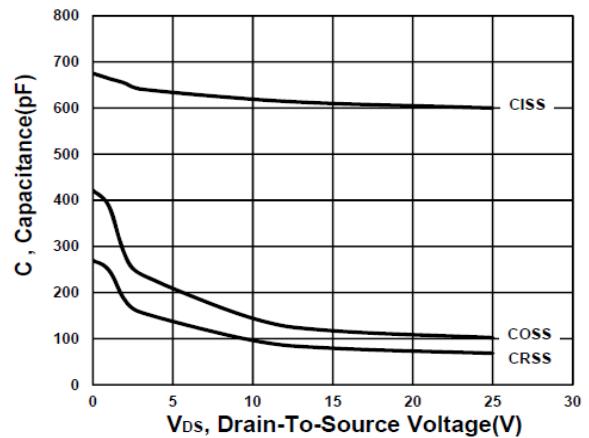
**Transfer Characteristics**



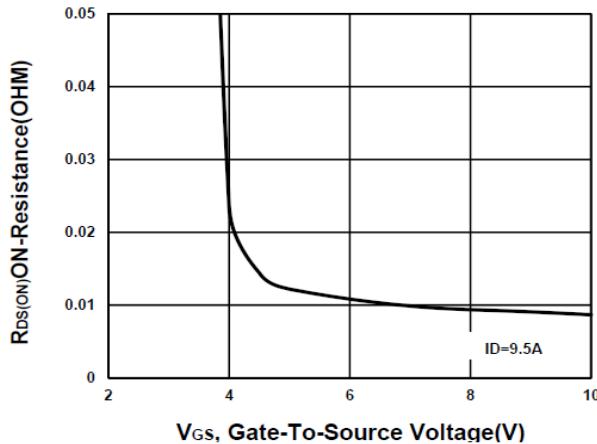
**Gate charge Characteristics**



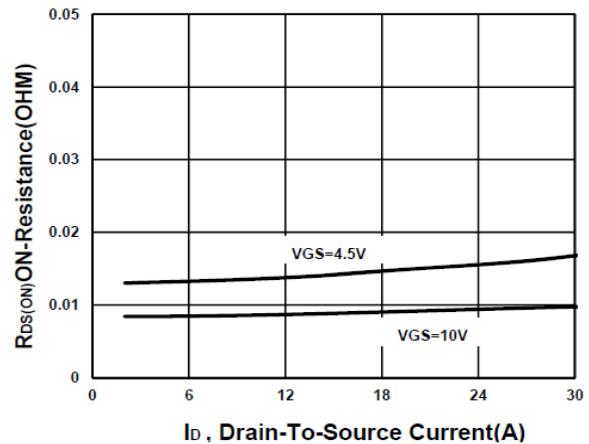
**Capacitance Characteristic**



**On-Resistance VS Gate-To-Source**

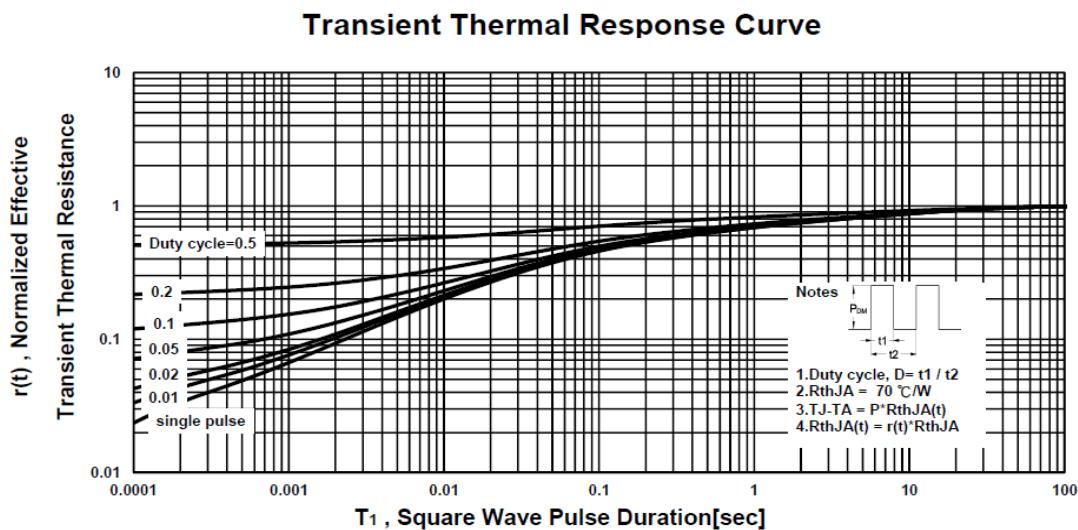
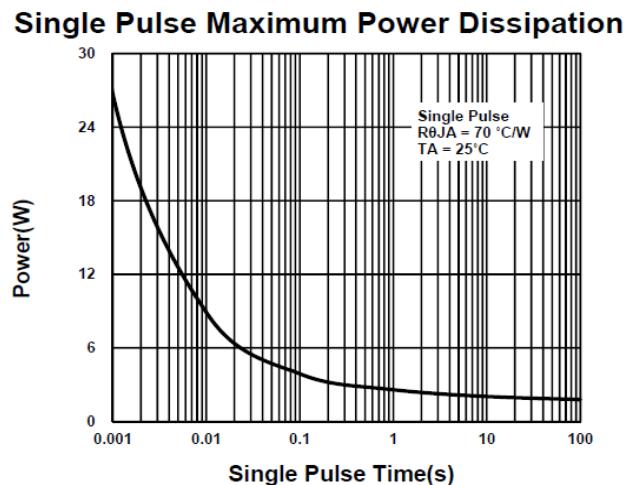
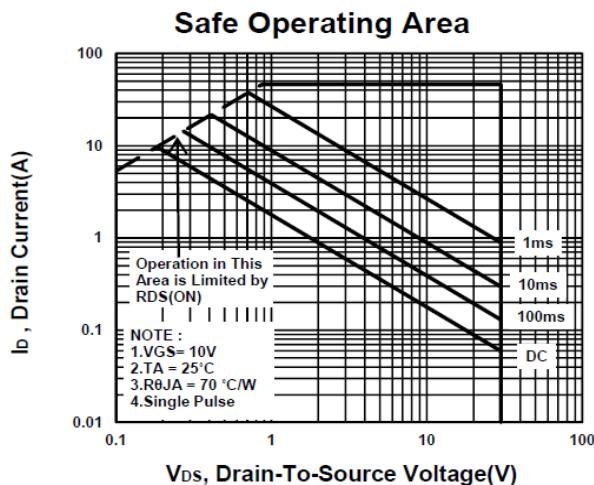
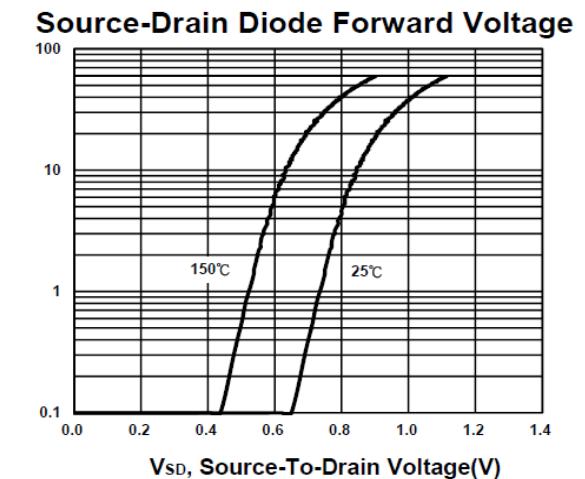
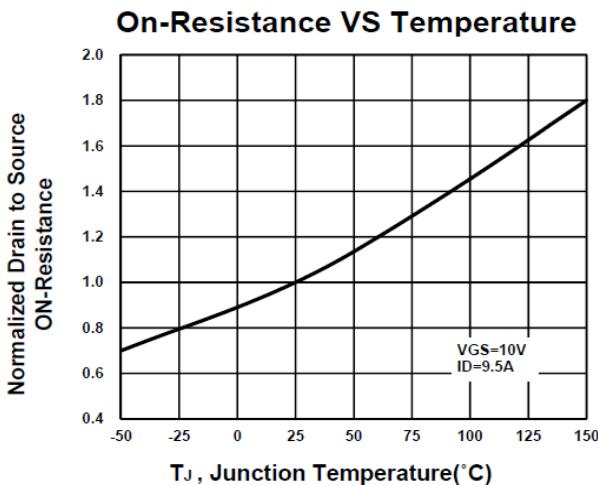


**On-Resistance VS Drain Current**



# PE642DT

## Dual N-Channel Enhancement Mode MOSFET



# PE642DT

## Dual N-Channel Enhancement Mode MOSFET

### Package Dimension

#### PDFN 3x3S(上下 Dual) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	2.9	3	3.1	I		0.25	
B	2.9	3	3.1	J	0.94	0.99	1.04
C	0.8	0.85	0.9	K	0.47	0.52	0.57
D	0.195	0.203	0.211	L	0.35	0.4	0.45
E	0		0.05				
F		0.65					
G	0.27	0.32	0.37				
H		1.86					

